SK35DGDL12T4 T



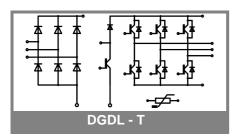
SEMITOP®4

3-phase bridge rectifier + brake chopper + 3-phase bridge inverter SK 35 DGDL 12T4 T

Target Data

Features

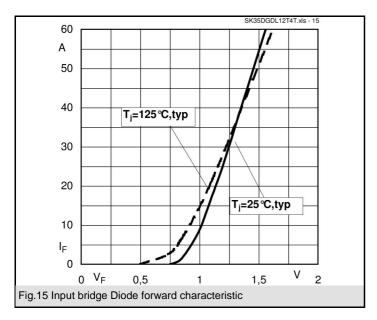
- One screw mounting module
- Fully compatible with SEMITOP®1,2,3
- Improved thermal performances by aluminium oxide substrate
- Trench4 IGBT technology
- CAL4 technology free-wheeling diode
- Integrated NTC temperature sensor
- 1) $V_{CE,sat}$, V_F = chip level value

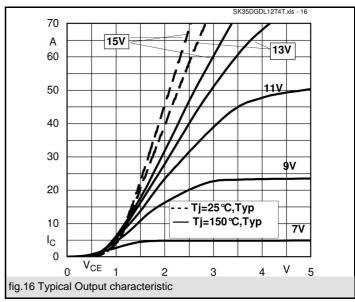


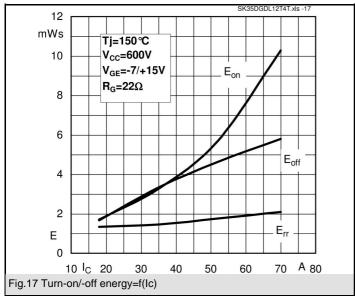
Absolute Maximum Ratings Ts = 25 °C, unless otherwise specifie								
Symbol	Conditions	Values	Units					
IGBT - Inverter,Chopper								
V_{CES}		1200	V					
I _C	T _s = 25 (70) °C	58 (46)	Α					
I _{CRM}	$I_{CRM} = 3 \times I_{Cnom}, t_p = 1 \text{ ms}$	105	Α					
V_{GES}		± 20	V					
T _j		-40 + 175	°C					
Diode - Inverter, Chopper								
I _F	T _s = 25 (70) °C	41 (33)	Α					
I _{FRM}	$I_{FRM} = 2xI_{Fnom}, t_p = 1 \text{ ms}$	105	Α					
T _j	·	-40 + 150	°C					
Rectifier								
V_{RRM}		1600	V					
I _F	T _s = 70 °C	46	Α					
I _{FSM} / I _{TSM}	$t_p = 10 \text{ ms}$, sin 180 ° , $T_j = 25 \text{ °C}$	370	Α					
I ² t	$t_p = 10 \text{ ms}$, sin 180 °, $T_j = 25 \text{ °C}$	684	A²s					
T _j		-40 + 175	°C					
T _{sol}	Terminals, 10 s	260	°C					
T _{stg}		-40 + 125	°C					
V _{isol}	AC, 1 min. / 1 s	2500 / 3000	V					

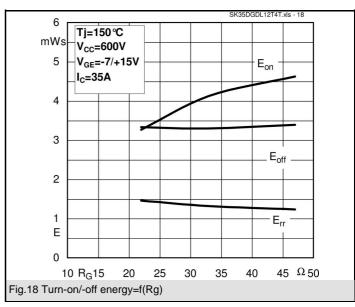
Characteristics		Ts = 25 °C, unless otherwise specified						
Symbol	Conditions	min.	typ.	max.	Units			
IGBT - Inverter								
V _{CEsat}	I _C = 35 A, T _j = 25 (150) °C		1,85 (2,2)	2,05 (2,45)	V			
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 1 \text{ mA}$	5	5,8	6,5	V			
$V_{CE(TO)}$	T _j = 25 °C (150) °C		1,1 (1)	1,3 (1,2)	V			
r _T	T _j = 25 °C (150) °C		22 (36)		mΩ			
C _{ies}	$V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz$		1,95		nF			
C _{oes}	$V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz$		0,155		nF			
C _{res}	$V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz$		0,115		nF			
R _{th(j-s)}	per IGBT		0,8		K/W			
t _{d(on)}	under following conditions		28		ns			
t _r	$V_{CC} = 600 \text{ V}, V_{GE} = \pm 15 \text{ V}$		25		ns			
t _{d(off)}	$I_C = 35 \text{ A}, T_j = 150 ^{\circ}\text{C}$		303		ns			
<u>t_f</u>	$R_{Gon} = R_{Goff} = 22 \Omega$		70		ns			
E _{on}	inductive load		3,27		mJ			
E _{off}			3,3		mJ			
Diode - Inv	Diode - Inverter, Chopper							
$V_F = V_{EC}$	I _F = 35 A, T _i = 25(150) °C		2,3 (2,3)	2,6 (2,6)	V			
V _(TO)	T _i = 25 °C (150) °C		1,3 (0,9)	1,5 (1,1)	V			
r _T	T _i = 25 °C (150) °C		29 (40)	32 (43)	mΩ			
$R_{th(j-s)}$	per diode		1,37		K/W			
I _{RRM}	under following conditions		30		Α			
Q_{rr}	I _F = 35 A, V _R = 600 V		2		μC			
E _{rr}	V _{GE} = 0 V, T _j = 150 °C		1,46		mJ			
	di _{F/dt} = 290 A/μs							
Diode - Rectifier								
V_{F}	I _F = 25 A, T _j = 25() °C		1,1		V			
$V_{(TO)}$	T _j = 150 °C		0,8		V			
r _T	T _j = 150 °C		13		mΩ			
$R_{th(j-s)}$	per diode		1,25		K/W			
Temperatu	ır sensor							
R _{ts}	5 %, T _r = 25 (100) °C		5000(493)		Ω			
Mechanica	al data	•						
w			60		g			
M_s	Mounting torque		3,5		Nm			

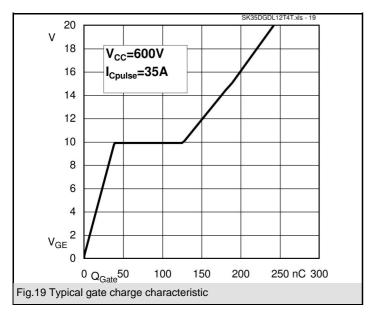
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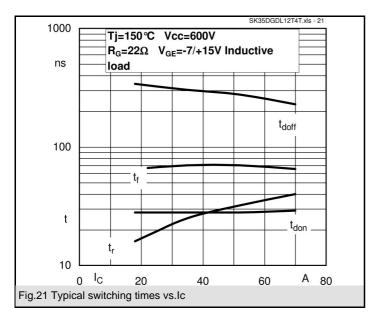


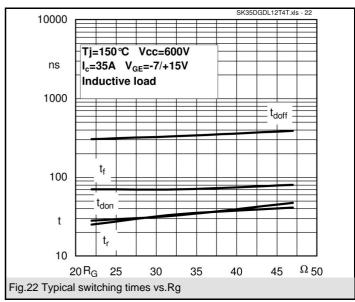


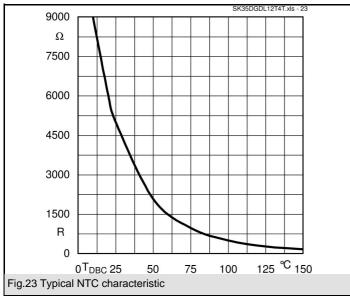


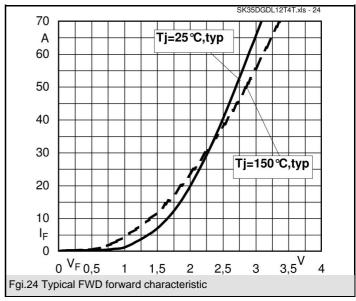


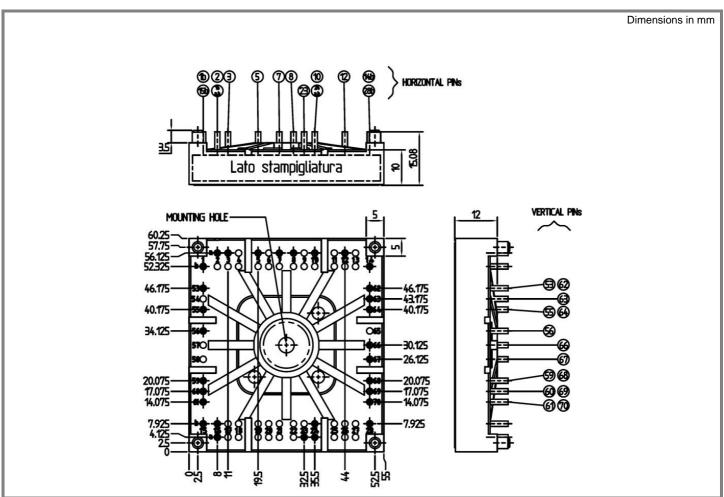
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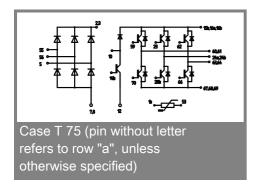








Case T 75 (Suggested hole diameter for the solder pins in the circuit board: 2mm. Suggested hole diameter for the mounting pins in the circuit board: 3,6mm)



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.